



Features

- Ideal for indication light on hand held products
- Long life and robust package
- White SMD package, silicone resin.
- Standard Package: 500pcs/ Reel
- \bullet MSL (Moisture Sensitivity Level): 3
- RoHS compliant.

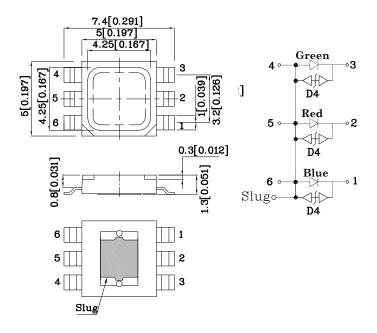


ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES





Package Schematics



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.15 [\pm 0.006]$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

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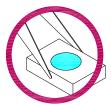


Handling Precautions

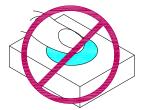
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

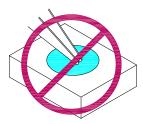
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

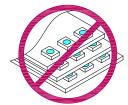


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.





3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

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5.0mm x 5.0mm SURFACE MOUNT LED LAMP

Selection Guide

Part Number	Emitting Color	Emitting Material	Lens-color	CIE127-2 (IF=15	Luminous Intensity CIE127-2007* [2] (IF=150mA) cd		uminous Fl E127-2007* IF=150mA lm	Viewing Angle 2 0 1/2 [1]	
				min.	typ.	min.	typ.	max.	
	Blue	InGaN		1*	1.59*	2.9*	4*	6	
XZCB25MO24DG25X111S	Red	AlGaInP	Water Clear	2.7*	4.29*	8.6*	10.7*	17	120°
_	Green	InGaN		4.2*	5.99*	12*	16.7*	29	

Notes:

- $1.\ \theta 1/2$ is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity/ luminous Flux: $\pm 1.5\%$. *LEDs are binned according to their luminous flux. *Luminous Intensity/Luminous Flux value is in accordance with CIE127-2007 standards.

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Emitting Color	Value	Unit	
		Blue	0.6		
Power dissipation	PD	Red	0.45	W	
		Green	0.6		
		Blue	110		
Junction temperature	TJ	Red	110	$^{\circ}\mathrm{C}$	
		Green	110		
		Blue		°C	
Operating Temperature	Тор	Red	-40 To +85		
		Green			
Storage Temperature		Blue		°C	
	Tstg	Red	-40 To +85		
		Green			
DC Forward Current [1]		Blue	150	mA	
	${ m IF}$	Red	150		
		Green	150		
Peak Forward Current [2]		Blue	300		
	IFM	Red	300	mA	
		Green	300		
Thermal resistance		Blue	220		
	Rth j-a	Red	270	°C/W	
		Green	200		
		Blue	25	°C/W	
Thermal resistance	Rth j-s	Red	40		
		Green	33		

Notes:

- 1. Results from mounting on Aluminum Board.
- $2.\ 1/10$ Duty Cycle, $0.1\mathrm{ms}$ Pulse Width.

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 $^{3.\} A\ Relative\ Humidity\ between\ 40\%\ and\ 60\%\ is\ recommended\ in\ ESD\-protected\ work\ areas\ to\ reduce\ static\ build\ up\ during\ assembly\ process\ (Reference\ JEDEC/loop)$ JESD625-A and JEDEC/J-STD-033)



5.0mm x 5.0mm SURFACE MOUNT LED LAMP

Electrical / Optical Characteristics at Ta=25°C

Parameter	C11	E		Value			
rarameter	Symbol	Emitting Color	Min.	Тур.	Max.	Unit	
Wavelength at peak emission CIE127-2007* IF=150mA		Blue		452*			
Wavelength at peak emission CIE127-2007* IF=150mA	λpeak	Red		635*		nm	
Wavelength at peak emission CIE127-2007* IF=150mA		Green		515*			
Dominant Wavelength CIE127-2007* IF=150mA		Blue		460*	473*	nm	
Dominant Wavelength CIE127-2007* IF=150mA	λdom [1]	Red		624*	-		
Dominant Wavelength CIE127-2007* IF=150mA		Green		525*	535*		
Spectral Line Half-width IF=150mA		Blue		20		nm	
Spectral Line Half-width IF=150mA	Δλ1/2	Red		20			
Spectral Line Half-width IF=150mA		Green		30			
Forward Voltage IF=150mA		Blue	3.0	3.5	4.0	V	
Forward Voltage IF=150mA	VF [2]	Red	2.0	2.5	3.0		
Forward Voltage IF=150mA		Green	3.0	3.5	4.0		
	VR	Blue			5	V	
Reverse Voltage		Red			5		
		Green			5		
Temperature coefficient of λpeak IF=150mA, -10°C≤ T≤100°C		Blue		0.12		nm/°C	
Temperature coefficient of λpeak I _F =150mA, -10°C≤ T≤100°C	TCλpeak	Red		0.09			
Temperature coefficient of λpeak IF=150mA, -10°C≤ T≤100°C		Green		0.13			
Temperature coefficient of λdom IF=150mA, -10°C≤ T≤100°C		Blue		0.1			
Temperature coefficient of λdom IF=150mA, -10°C≤ T≤100°C	TCλdom	Red		0.03		nm/°C	
Temperature coefficient of λdom IF=150mA, -10°C≤ T≤100°C		Green		0.11			
Temperature coefficient of VF IF=150mA, -10°C≤ T≤100°C		Blue		-2.3			
Temperature coefficient of VF IF=150mA, -10°C≤ T≤100°C	TCv	Red		-2.7		mV/°C	
Temperature coefficient of VF IF=150mA, -10°C≤ T≤100°C		Green		-3.9		-	

Notes:

1.Wavelength: +/-1nm.

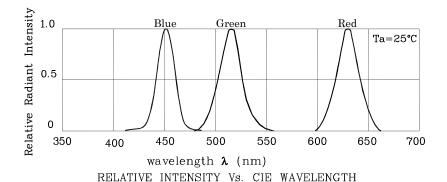
2. Forward Voltage: +/-0.2V.

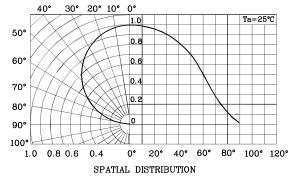
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^{*}wavelength is in accordance with CIE127-2007 standards.

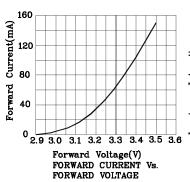


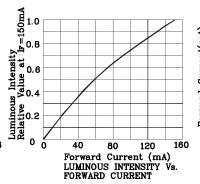


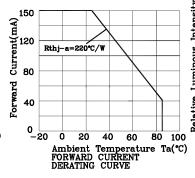


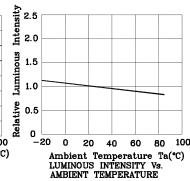


❖ Blue

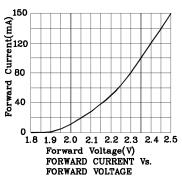


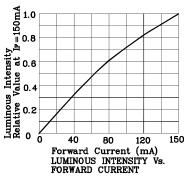


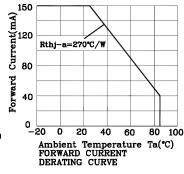


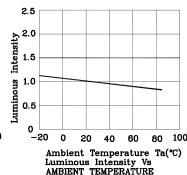


* Red

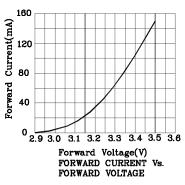


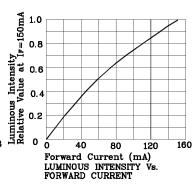


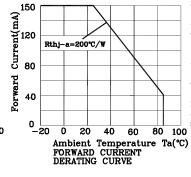


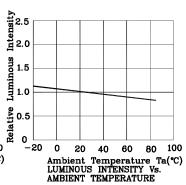


❖ Green







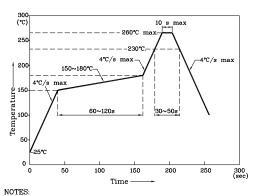






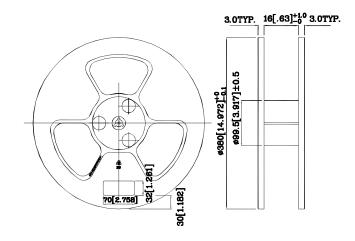
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



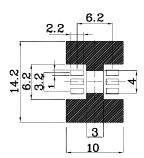
- Maximum soldering temperature should not exceed 260°c.
- 2. Recommended reflow temperature: 145°c-260°c.
- Do not put stress to the epoxy resin during high temperatures conditions.

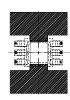
Reel Dimension



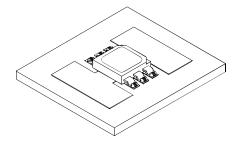
♦ The device has a single mounting surface. The device must be mounted according to the specifications.

♦ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

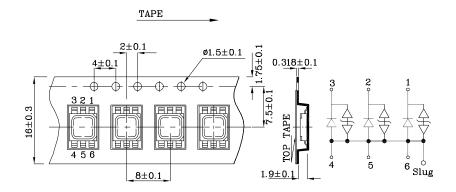




Solder Mask



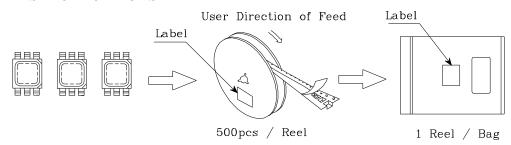
* Tape Specification (Units:mm)

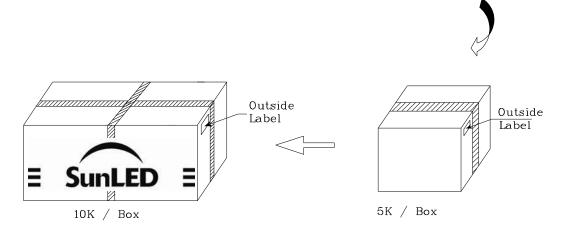


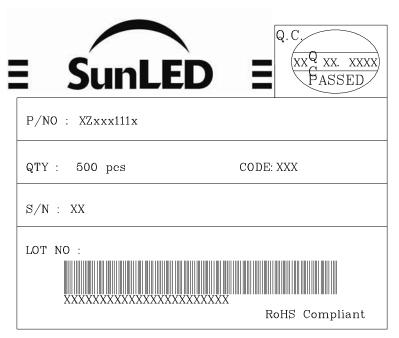




PACKING & LABEL SPECIFICATIONS







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